

Industrial 3D TLC NAND M.2 2280 NVMe SSD

MEC3H0E SERIES

PCle Gen4x4

DRAM-less

3K PE Cycles

R/W: 4,700 / 3,800 MB/s



PRODUCT FEATURES

- High-Quality 112-layer 3D TLC NAND Flash Technology.
- Industrial Standard PCIe Gen4x4 with NVMe 1.4 Compliant.
- Support TRIM command to remove data not in use to keep optimized performance.
- Dynamic SLC caching algorithm to deliver the better sustained performance.
- When SSD is going to worn-out to activate Read Only Mode to prevent further data corruption.
- Lifetime Enhancements

Support Both Dynamic wear leveling and Static wear leveling.

Early bad block detect and Later bad block management.

Over-provisioning to reserve extra space to enhance reliability and endurance. (by request)

Block/Page RAID function to ensure data recovery.

- Reliable Industrial grade integrated Active PMU and complete protection design with OVP, OCP, surge rejection and Short protection.
- Power shielding firmware architecture to ensure power failure resilience.
- SP SMART Toolbox.
- SP SMART Embedded and SMART IoT service. (by request)
- Driven by a growing number of IOPS in heavy data applications, the biggest benefit of PCIe-based SSD is increased performance.

 Reach up to R:4700 MB/s and W:3800 MB/s based on 16CE NAND flash.

PRODUCT SUMMARY

Capacities: 256GB, 512GB, 1TB

Form Factor: M.2 2280 PCle Solid State Drive (80 mm x 22 mm x 3.5 mm)

Compliance: PCle Gen 4x4 compliant with Gen1,2,3.

- Command Sets : NVMe1.4 standard command protocol.
- Performance :

	256GB	512GB	1TB
Sequential Read (MB/s Max.)	3,800	4,700	4,700
Sequential Write (MB/s Max.)	1,700	3,400	3,800
Random 4K Read (IOPS Max.)	200,000	450,000	570,000
Random 4K Write (IOPS Max.)	400,000	550,000	600,000

^{*} Actual performance may vary based on the specific model and capacity

· Operating Temperature Range:

Normal: 0°C to 70°C

Storage Temperature Range: -55°C to 95°C

Operating Voltage: 3.3 V ± 10%

Power Consumption:

(Unit: W)	256GB	512GB	1TB	
Read (Max.)	TBD	TBD	TBD	
Write (Max.)	TBD	TBD	TBD	
Stand-by (Avg.)	TBD	TBD	TBD	

^{*} Actual value may vary based on the specific model and capacity

- Data Retention @40 °C: 10 Years @ Life Begin; 1 Year @ Life End
- Endurance in Tera Bytes Written (TBW): (Unit: TB)

Workload	256GB	512GB	1TB	
Sequential	>200	>300	>600	
Enterprise	TBD	TBD	TBD	

TBW is estimated by formula TBW = (Capacity x PE Cycles) x (1+OP) x (WLE) / (WAF)

OP (Over Provision) = (Physical Capacity / Logical Capacity)-1

WAF = Write Amplification Factor

WLE = Wear Leveling Efficiency could be different depended on the workload or usage containing data size and access rate.

Sequential workload: Sequential write workload which is generated by VDBENCH script and tested by VDBENCH

Enterprise workload: Follow JESD219A enterprise workload which is generated by VDBENCH script and tested by VDBENCH.

Mechanical (IEC-60068):

Vibration : 15G, 10 ~ 2001Hz

Drop: 76cm

Shock: 1.500G@0.6ms

- LDPC ECC engine and Block/Page RAID to ensure reliable 3K PE cycles
- Mean Time Between Failure: > 2,000,000 hours
- Data Reliability: Non-recover Read (UBER) ≤10⁻¹⁶
- Serious quality control and assurance

100% NAND Flash screening

High endurance product design with 3D NAND product offerings

Implement high/low temperature dynamic burn-in in each lot production to monitor production quality to meet design specification Reliability criteria compliant with international standards IEC-60068/61000

